

R560 Solder Paste

Water Soluble

Product Description

Kester R560 is an organic acid, water soluble solder paste formula specifically designed to reduce voiding in Ball Grid Array (BGA) solder connections. The voiding in BGAs is shown to be reduced from 25% to less than 5%. R560 is also resistant to extremes in temperature and relative humidity. R560 is designed to be slump resistant in high humidity conditions. The solder paste exhibits long stencil life and tack time, while still delivering exceptional solderability to a wide variety of metallic substrates. The activator package in this formula is very aggressive, providing superior wetting to OSP coated boards and Ag/Pd leaded components. R560 is an extremely stable water soluble formula.

Performance Characteristics:

- Reduces BGA voiding to under 5%
- 8 hour stencil life
- Consistent printing over a range of temperatures and humidity levels
- Wets excellently to Ag/Pd leaded components
- Reduces scrap due to less paste dry out
- Residues easily removed with hot DI water
- Classified as ORHO per J-STD-004
- Compatible with enclosed printing systems

Standard Applications:

90% Metal - Stencil Printing

90% Metal - Enclosed Head Printing

Physical Properties

(Data given for Sn63Pb3, 790% metal, -325+500 mesh)

Viscosity (typical): 1900 poise

Malcom Viscometer @ 10 rpm and 25 °C

Initial Tackiness (typical): 45 grams

Tested to J-STD-005, IPC-TM-650, Method 2.4.44

Slump Test: Pass

Tested to J-STD-005, IPC-TM-650, Method 2.4.35

Solder Ball Test: Preferred

Tested to J-STD-005, IPC-TM-650, Method 2.4.43

Wetting: Pass

Tested to J-STD-005, IPC-TM-650, Method 2.4.45

Reliability Properties**Copper Mirror Corrosion:** High

Tested to J-STD-004, IPC-TM-650, Method 2.3.32

Corrosion Test: Low

Tested to J-STD-004, IPC-TM-650, Method 2.6.15

Silver Chromate: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.33

Chloride and Bromides: None Detected

Tested to J-STD-004, IPC-TM-650, Method 2.3.35

Fluorides by Spot Test: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

Surface Insulation Resistivity (SIR): Pass

Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3

	Blank	R560
Day 1	$2.76 \times 10^9 \Omega$	$4.60 \times 10^8 \Omega$
Day 4	$1.32 \times 10^9 \Omega$	$1.97 \times 10^9 \Omega$
Day 7	$1.22 \times 10^9 \Omega$	$3.04 \times 10^9 \Omega$

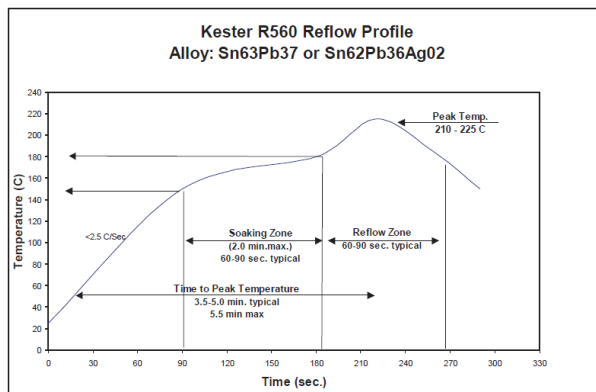
Availability

R560 is commonly available in the Sn63Pb37 and Sn62Pb36Ag02 alloys. Type 3 powder mesh is recommended, but different powder particle size distributions are available for standard and fine pitch applications. R560 is compatible with enclosed print head systems. For specific packaging information on available sizes visit the R560 Product Offerings page at Kester.com. The appropriate combination depends on process variables and the specific application.

Printing Parameters

Printing Process Parameters	Recommendations
Squeegee Blade	80 to 90 durometer polyurethane or stainless steel
Squeegee Speed	Capable to a maximum speed of 50 mm/sec (2 in/sec)
Stencil Material	Stainless Steel, Molybdenum, Nickel Plated, Brass
Temperature/Humidity	Optimal ranges are 21 to 25 °C (70 to 77 °F) and 35 to 65% RH

Recommended Reflow Profile



The recommended reflow profile for R560 made with either the Sn63Pb37 or Sn62Pb36Ag02 is shown here. This profile is simply a guideline.

Since R560 is a highly active, water soluble solder paste, it can solder effectively over a wide range of profiles. Your optimal profile may be different from the one shown based on your oven, board and mix of defects.

Please contact Kester Technical Support if you need additional profiling advice.

Cleaning

R560 residues are best removed using automated cleaning equipment (in-line or batch) within 24 hours of soldering. Deionized water is recommended for the final rinse. Water temperatures should be 49 to 60 °C (120 to 140 °F). Kester's 5768 Bio-Kleen[®] saponifier can also be used in a 1 to 2% ratio for aqueous cleaning systems.

Storage, Handling and Shelf Life

Refrigeration is the recommended optimum storage condition for solder paste to maintain consistent viscosity, reflow characteristics and overall performance. R560 should be stabilized at room temperature prior to printing. R560 should be kept at standard refrigeration conditions, 0 to 10°C (32 to 50 °F). Please contact Kester if you require additional advice with regard storage and handling of this material. Shelf life is 6 months from date of manufacture when handled properly and held at 0 to 10 °C (32 to 50 °F).

Health and Safety

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet and warning label before using this product. Safety Data Sheets are available at <https://www.kester.com/downloads/sds>.

Contact Information

To confirm this document is the most recent version, please contact Assembly@MacDermidAlpha.com

North America 800 West Thorndale Avenue Itasca, IL USA 60143 Phone: +1 800.2.KESTER	Asia Pacific 8/F., Paul Y. Centre 51 Hung To Road Kwun Tong, Kowloon, Hong Kong Phone: +852.3190.3100	Europe Ganghofer Strasse 45 82216 Gernlinden, Germany Phone: +49 (0) 8142 4785 0
---	--	--

Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE. Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588

DISCLAIMER: All statements, technical information and recommendations contained herein are based on tests we believe to be reliable, but the accuracy or completeness thereof is not guaranteed. No statement or recommendation shall constitute a representation unless set forth in an agreement signed by officers of seller and manufacturer. NO WARRANTY OF MERCHANTABILITY, WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE OR ANY IMPLIED WARRANTY IS MADE. The following warranty is made in lieu of such warranties and all other warranties, express, implied, or statutory. Products are warranted to be free from defects in material and workmanship at the time sold. The sole obligation of seller and manufacturer under this warranty shall be to replace any noncompliant product at the time sold. Under no circumstances shall manufacturer or seller be liable for any loss, damage or expense, direct, indirect, incidental or consequential, arising out of the inability to use the product. Notwithstanding the foregoing, if products are supplied in response to a customer request that specifies operating parameters beyond those stated above, or if products are used under conditions exceeding said parameters, the customer by acceptance or use thereof assumes all risk of product failure and of all direct, indirect, incidental and consequential damages that may result from use of the products under such conditions, and agrees to exonerate, indemnify, defend and hold harmless MacDermid, Incorporated and its affiliates therefrom. No suggestion for product use nor anything contained herein shall be construed as a recommendation to use any product in a manner that infringes any patent or other intellectual property rights, and seller and manufacturer assume no responsibility or liability for any such infringement.

© 2019 MacDermid, Inc. and its group of companies. All rights reserved. "R" and "TM" are registered trademarks of MacDermid, Inc. and its group of companies in the United States and/or other countries.